

ABSTRACT

An apparatus and method for polishing objects, such as semiconductor wafers, utilizes one or more pivotable load-and-unload cups to transfer the objects to and/or from one or more object carriers to polish the objects. Each pivotable load-and-unload cup may be configured to transfer the objects to and/or from a single object carrier. Alternatively, each pivotable load-and-unload cup may be configured to transfer the objects to and/or from two object carriers. The pivotable load-and-unload cups may be configured to be pivoted about one or more pivoting points over at least one polishing surface, such as a polishing pad surface.